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INFORMATION DISCLOSURE Complete if Known 10/602,323 **Application Number** STATEMENT BY APPLICANT June 24, 2003 Filing Date First Named Inventor Ahn, Kie SEP & 8 701.5 **Group Art Unit** 2823 **Examiner Name** Toledo, Fernando Attorney Docket No: 1303.101US1 Sheet 1 of 3

USP Document Number Publication Name of Patentee or Applicant of cited Document Filing III Appr	
VB-2003/0045060-A1 03/06/2003 Ahn, Kie Y. 08/30/20 US-2003/0045078-A1 03/06/2003 Ahn, Kie Y., et al. 08/30/20 US-2003/0049942-A1 03/13/2003 Haukka, S., et al. 08/22/20 US-2003/01094666-A1 06/05/2003 Luo, L., et al. 09/25/20 US-2003/0119246-A1 06/05/2003 Ahn, Kie Y. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0185980-A1 10/17/2003 Ahn, Kie Y. 01/17/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/30/20 US-2004/0003461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0033651-A1 02/19/2004 Yeo, J., et al. 06/02/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/21/20 US-2004/0043559-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0043559-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/01043635-A1 03/04/2004	
US-2003/0045078-A1 03/06/2003 Ahn, Kie Y., et al. 08/30/20 US-2003/0049942-A1 03/13/2003 Haukka, S., et al. 08/22/20 US-2003/0059535-A1 03/27/2003 Luo, L., et al. 09/25/20 US-2003/0104666-A1 06/05/2003 Bojarczuk, Jr., N. A., et al. 12/20/20 US-2003/0119246-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/003861-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0038651-A1 02/25/2004 Ahn, Kie Y. 08/21/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/21/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/0043635-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0043635-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110348-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0164356-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/017280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/017380-A1 09/23/2004 Ahn, Kie Y.)2 ·
US-2003/0049942-A1 03/13/2003 Haukka, S., et al. 08/22/20 US-2003/0059535-A1 03/27/2003 Luo, L., et al. 09/25/20 US-2003/0104666-A1 06/05/2003 Bojarczuk, Jr., N. A., et al. 12/20/20 US-2003/0119246-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 07/30/20 US-2004/0033654-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/003354-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0043635-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110391-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/017882-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/017882-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0186654-A1 09/23/2004 Ahn, Kie Y.)1
US-2003/0059535-A1 03/27/2003 Luo, L. , et al. 09/25/20 US-2003/0104666-A1 06/05/2003 Bojarczuk, Jr., N. A., et al. 12/20/20 US-2003/0119246-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J. , et al. 07/10/20 US-2004/0009679-A1 01/15/2004 Yeo, J. , et al. 07/10/20 US-2004/0033661-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/0043561-A1 03/04/2004 Ahn, Kie Y. 08/21/20 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0043635-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/011038-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0175882-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0175882-A1 09/02/2004 Conley, Jr., J. F., et al. 03/04/200 US-2004/0175882-A1 09/02/2004 Conley, Jr., J. F., et al. 03/04/200 US-2004/0175882-A1 09/02/2004 Conley, Jr., J. F., et al. 03/04/200 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0175862-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/023551-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/023551-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200)4
US-2003/0104666-A1 06/05/2003 Bojarczuk, Jr., N. A., et al. 12/20/20 US-2003/0119246-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y., et al. 01/17/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 07/30/20 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/004369-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/01348-A1 06/10/2004 Ahn, Kie Y. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110391-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/017280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/017882-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0186654-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0186654-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0186654-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0186654-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0186654-A1 09/02/2004 Conley, Jr., J. F., et al. 04/11/20 US-2004/0185654-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/20)2
US-2003/0119246-A1 06/26/2003 Ahn, Kie Y. 12/20/20 US-2003/0119291-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/200 US-2003/0132491-A1 10/02/2003 Endo, K. 03/31/200 US-2004/009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/009661-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/200 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/200 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/200 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/200 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/01043635-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/01043635-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0164357-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0185654-A1 09/02/2004 Conley, Jr., J. F., et al. 03/04/200 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0185654-A1 09/02/2004 Ahn, Kie Y. et al. 04/11/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200	<u> </u>
US-2003/0119291-A1 06/26/2003 Ahn, Kie Y., et al. 12/20/20 US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/20 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/20 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/004365-A1 03/04/2004 Vaartstra, B. A. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0164365-A1 08/26/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0175882-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/20 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/20)2
US-2003/0132491-A1 07/17/2003 Ahn, Kie Y. 01/17/200 US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/200 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/200 US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/200 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/200 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/200 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/010348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0110391-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0183108-A1 09/02/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0183108-A1 09/03/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0185654-A1 10/14/2004 Conley, Jr., J. F., et al. 03/04/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200)1
US-2003/0185980-A1 10/02/2003 Endo, K. 03/31/20 US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/20 US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/20 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/20 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/20 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/20 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/20 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/20 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0110391-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/20 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/20 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 02/27/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/20 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/020325313-A1 11/25/2004 Frank, M. M., et al. 06/24/200	<u>)1</u>
US-2004/0009679-A1 01/15/2004 Yeo, J., et al. 07/10/200 US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/200 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/200 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/200 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/200 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0110391-A1 06/10/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/017280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/017882-A1 09/09/2004 Ahn, Kie Y. 01/27/200 US-2004/0183108-A1 09/02/2004 Ahn, Kie Y. 01/27/200 US-2004/018)2
US-2004/0023461-A1 02/05/2004 Ahn, Kie Y., et al. 07/30/200 US-2004/0033661-A1 02/19/2004 Yeo, J., et al. 06/02/200 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/200 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/200 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 03/04/200 US-2004/0185654-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)3
US-2004/0038654-A1 02/19/2004 Yeo, J., et al. 06/02/2004 US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/2004 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/2004 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/2004 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/2004 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/2004 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/2004 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/020325313-A1 11/25/2004 Frank, M. M., et al. 06/24/2004 US-2004/020325313-A1 11/25/2004 Frank, M. M., et al. 06/24/2004)3
US-2004/0038554-A1 02/26/2004 Ahn, Kie Y. 08/21/2004 US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/2004 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/2004 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/2004 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/2004 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/2004 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 12/04/2004 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 01/27/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. et al. 01/27/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203253313-A1 11/25/2004 Frank, M. M., et al. 06/24/2004)2
US-2004/0043541-A1 03/04/2004 Ahn, Kie Y. 08/29/200 US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/200 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/200 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)3
US-2004/0043569-A1 03/04/2004 Ahn, Kie Y. 08/28/2004 US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/2004 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/2004 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/2004 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/27/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/020325313-A1 11/25/2004 Frank, M. M., et al. 06/24/2006)2
US-2004/0043635-A1 03/04/2004 Vaartstra, B. A. 08/28/200 US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/200 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)2
US-2004/0110348-A1 06/10/2004 Ahn, Kie Y., et al. 12/04/2004 US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/2004 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/2004 US-2004/0175882-A1 09/02/2004 Ahn, Kie Y., et al. 02/27/2004 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y., et al. 03/04/2004 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/27/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/2004 US-2004/0203254-A1 11/25/2004 Frank, M. M., et al. 06/24/2004)2
US-2004/0110391-A1 06/10/2004 Ahn, K. Y., et al. 12/04/200 US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)2
US-2004/0164357-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)2
US-2004/0164365-A1 08/26/2004 Ahn, Kie Y., et al. 02/27/200 US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)2
US-2004/0168627-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)4
US-2004/0171280-A1 09/02/2004 Conley, Jr., J. F., et al. 02/27/200 US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)4
US-2004/0175882-A1 09/09/2004 Ahn, Kie Y., et al. 03/04/200 US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)3
US-2004/0183108-A1 09/23/2004 Ahn, Kie Y. 01/27/200 US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200)3
US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200	
US-2004/0185654-A1 09/23/2004 Ahn, Kie Y. 01/30/200 US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200	
US-2004/0203254-A1 10/14/2004 Conley, Jr., J. F., et al. 04/11/200 US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200	
US-2004/0235313-A1 11/25/2004 Frank, M. M., et al. 06/24/200	
US-2004/0266217-A1 12/30/2004 Kim K et al 06/23/200	
 	
US-2005/0009370-A1 01/13/2005 Ahn, Kie Y. 08/04/200	
US-2005/0023574-A1 02/03/2005 Forbes, L., et al. 09/02/200	
US-2005/0026458-A1 02/03/2005 Basceri, C., et al. 08/26/200	
US-2005/0030825-A1 02/10/2005 Ahn, K. Y. 08/31/200	
US-2005/0037563-A1 02/17/2005 Ahn, Kie Y. 08/31/200	
US-2005/0054165-A1 03/10/2005 Ahn, K. Y., et al. 03/31/200	
US-2005/0077519-A1 04/14/2005 Ahn, Kie , et al. 10/10/200	
US-2005/0124174-A1 06/09/2005 Ahn, K. Y., et al. 01/07/200	
US-2005/0145957-A1 07/07/2005 Ahn, K. Y., et al. 02/16/200	
// US-2005/0158973-A1 07/21/2005 Ahn, K. Y., et al. 01/14/200	
US-2005/0164521-A1 07/28/2005 Ahn, Kie Y., et-al. 03/21/200	

EXAMINER

PTO/SB08A(10-01)
Approved for use through 10/31/2002, OAB 651-0001
US Patent & Tradement 00to: US, DEPARTMENT OF COMMERCE
and information unless it working a unit of the comment.

Substitute for form 1449A/PTO	Under the Paparwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid CMS control number. Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	10/602,323	
(Use as many sheets as necessary)	Filing Date	June 24, 2003	
	First Named Inventor	Ahn, Kie	
	Group Art Unit	2823	
	Examiner Name	Toledo, Fernando	
Sheet 2 of 3	Attorney Docket No: 1303.101US1		

	US PATENT DOCUMENTS				
Examiner initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate	
this	US-6,509,280	01/21/2003	Choi, Sung-Je	02/13/2002	
(US-6,541,079	04/01/2003	Bojarczuk, Jr., N. A., et al.	10/25/1999	
	US-6,551,929	04/22/2003	Kori, M., et al.	06/28/2000	
	US-6,592,942	07/15/2003	Van Wijck, M. A.	07/07/2000	
	US-6,638,859	10/28/2003	Sneh, O., et al.	09/27/2002	
	US-6,652,924	11/25/2003	Sherman, A.	05/24/2001	
	US-6,686,212	02/03/2004	Conley, Jr., J. F., et al.	10/31/2002	
	US-6,709,989	03/23/2004	Ramdani, J., et al.	06/21/2001	
	US-6,770,536	08/03/2004	Wilk, G. D., et al.	10/03/2002	
	US-6,777,353	08/17/2004	Putkonen, M.	04/08/2003	
	US-6,787,370	09/07/2004	Forbes, Leonard	12/16/2002	
	US-6,787,413	09/07/2004	Ahn, Kie Y.	06/17/2002	
	US-6,790,791	09/14/2004	Ahn, Kie Y., et al.	08/15/2002	
	US-6,800,567	10/05/2004	Cho, H. J.	08/22/2002	
	US-6,803,311	10/12/2004	Choi, E.	12/27/2002	
	US-6,812,100	11/02/2004	Ahn, K. Y., et al.	03/13/2002	
	US-6,844,260	01/18/2005	Sarigiannis, D., et al.	01/30/2003	
	US-6,858,444	02/22/2005	Ahn, K. Y., et al.	06/20/2003	
	US-6,884,739	04/26/2005	Ahn, K. Y., et al.	08/15/2002	
	US-6,893,984	05/17/2005	Ahn, K. Y., et al.	02/20/2002	
	US-6,900,122	05/31/2005	Ahn, K. Y., et al.	12/20/2001	
	US-6,914,800	07/05/2005	Ahn, K. Y., et al.	08/31/2004	
De l	US-6,921,702	07/26/2005	Ahn, K. Y., et al.	07/30/2002	
the	US-6,930,346	08/16/2005	Ahn, K. Y., et al.	08/31/2004	

FOREIGN PATENT DOCUMENTS				
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
			Document	

	OTHER	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner iņitials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T
M		AHN, KIE Y., et al., "ALD OF AMORPHOUS LANTHANIDE DOPED TIOX FILMS", U.S. Application Serial No. 11/092,072; filed March 29, 2005	
M		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITED HAFNIUM TANTALUM OXIDE DIELECTRICS", U.S. Application Serial No. 11/029,757; filed January 5, 2005	
by		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITED LANTHANUM ALUMINUM OXIDE DIELECTRIC LAYER", U.S. Application Serial No. 10/930,167; filed August 31, 2004	

EXAMINER TO COLOR

DATE CONSIDERED

PTO/SB/08A(10-01)
Approved for use through 10/31/2002, CMB 651-0031
US Petert & Tredemat Office: U.S. DEPARTMENT OF COMMERCE
on of information.

Substitute for form 1449A/PTO	Under the Peperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	10/602,323	
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	Examiner Name	Toledo, Fernando	
Sheet 3 of 3	Attorney Docket No: 1303.101US1		

	OTHER	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T.
Lit		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITED LANTHANUM HAFNIUM OXIDE DIELECTRICS", U.S. Application Serial No. 11/010,529; filed December 13, 2004	
		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITED TITANIUM ALUMINUM OXIDE FILMS", U.S. Application Serial No. 10/931,533; filed August 31, 2004	
·	_	AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITION OF Hf3N4/HfO2 FILMS AS GATE DIELECTRICS", U.S. Application Serial No. 11/063,717; filed February 23, 2005	
		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITION OF ZIRCONIUM-DOPED TANTALUM OXIDE FILMS", U.S. Application Serial No. 10/909,959; filed August 2, 2004	-
		AHN, KIE Y., et al., "ATOMIC LAYER DEPOSITION OF Zr3N4/ZrO2 FILMS AS GATE DIELECTRICS", U.S. Application Serial No. 11/058,563; filed February 15, 2005	
		AHN, KIE Y., et al., "HYBRID ALD-CVD OF PrXOY/ZrO2 FILMS AS GATE DIELECTRICS", U.S. Application Serial No. 11/010,766; filed December 13, 2004	
		AHN, KIE Y., et al., "RUTHENIUM GATE FOR A LANTHANIDE OXIDE DIELECTRIC LAYER", U.S. Application Serial No. 10/926,812; filed August 26, 2004	
MI		WILK, G. D., et al., "High-K gate dielectrics: Current status and materials properties considerations", <u>Journal of Applied Physics</u> , 89(10), (May 2001), 5243-5275	

EXAMINER TA COURTS

DATE CONSIDERED 11/23/05